**TI Designs: <TIDM-FRAM- WATERMETER >**

**Power Supply**

**Sensor Interface**

**Valve Control**
**TI Designs: <TIDM-FRAM-WATERMETER>**

- **LCD**: 
  - GND
  - 8.2pF C12
  - 8.2pF C13
  - 8.2pF C14
  - 8.2pF C15
  - 8.2pF C16
  - 8.2pF C17
  - 8.2pF C18
  - 8.2pF C19
  - 8.2pF C20
  - 8.2pF C21
  - 8.2pF C22
  - 8.2pF C23
  - 8.2pF C24

- **Boosterpack Interface**: 
  - GND
  - 0.1uF C52
  - GPIO2
  - SCLK
  - GPIO0
  - CSN
  - SIMO
  - SOMIRST_N

- **RS485**: 
  - VCC_LDO
  - 4
  - 3
  - 2
  - 1
  - 5
  - 6
  - 7
  - 8
  - 9
  - 10
  - J11
  - SN65HVD75
  - A
  - B
  - GND
  - 3
  - 4
  - 1
  - 2
  - Q2
  - VCC_485
  - D
  - GND
  - 4
  - 1
  - 2
  - 3
  - 5
  - 6
  - 7
  - 8
  - 9
  - 10
  - 11
  - 12

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